

Product Compliance Declaration

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Contact Information

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Part Information

Part Number 0349126080 **Part Weight** 2.174324G

Part Name MINI50 RAHDR SMT 8CKT BLK POL A T&R

Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
MINI50 RAHDR SMT 8CKT BLK POL A T&R	Assembly		100	2.174324
MINI50 HSNG RAHDR SMT 8CKT BLK POL A	Component		78.1852	1.7
PS-ST GF30 Black	Material		78.1852	1.7
PS-ST	Substance		45.6918	0.993487
GF-Fibre	Substance		23.5933	0.512995
Pigment portion, not to declare	Substance	system	0.5185	0.011274
Further Additives, not to declare	Substance	system	2.4144	0.052498
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	5.9672	0.129746
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	Component		6.1168	0.133
Cartridge Brass 70% Unplated	Material		5.7489	0.125
Copper	Substance	7440-50-8	4.0242	0.0875
Zinc (metal)	Substance	7440-66-6	1.7247	0.0375
Nickel Plating	Material		0.1288	0.0028

Form Rev - F

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Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.1288	0.0028
Further Additives, not to declare	Substance	system	1E-05	3E-07
Tin Plating	Material		0.2392	0.0052
Tin	Substance	7440-31-5	0.2392	0.0052
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	Component		5.7489	0.125
Cartridge Brass 70% Unplated	Material		5.381	0.117
Copper	Substance	7440-50-8	3.7667	0.0819
Zinc (metal)	Substance	7440-66-6	1.6143	0.0351
Nickel Plating	Material		0.1288	0.0028
Nickel	Substance	7440-02-0	0.1288	0.0028
Further Additives, not to declare	Substance	system	1E-05	3E-07
Tin Plating	Material		0.2392	0.0052
Tin	Substance	7440-31-5	0.2392	0.0052
MINI50 TERM BLD 0.50X15.57 AU	Component		9.949	0.216324
Cartridge Brass 70% Unplated	Material		8.8303	0.192
Copper	Substance	7440-50-8	6.1812	0.1344
Zinc (metal)	Substance	7440-66-6	2.6491	0.0576
Nickel Plating	Material		0.5887	0.0128
Nickel	Substance	7440-02-0	0.5886	0.012799
Further Additives, not to declare	Substance	system	6E-05	0.000001
Tin Plating	Material		0.3492	0.007594
Tin	Substance	7440-31-5	0.3492	0.007594
Gold Plating	Material		0.1808	0.00393
Cobalt	Substance	7440-48-4	0.0005	0.00001
Nickel	Substance	7440-02-0	0.0005	0.00001
Gold	Substance	7440-57-5	0.1799	0.003911

Form Rev - F

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ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)4578-DC (25 June 2020)

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
benzo[ghi]perylene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
tricosafuorododecanoic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Octanoic acid, 2,2,3,3,4,4,5,5,6,6,7,7,8,8,8-pentadecafluoro-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
heptacosafuorotetradecanoic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dodecamethylcyclhexasiloxane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
decamethylcyclopentasiloxane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
benzene-1,2,4-tricarboxylic acid 1,2-anhydride	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
octamethylcyclotetrasiloxane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
disodium 3,3'-[[1,1'-biphenyl]-4,4'-diylbis(azo)]bis(4-aminonaphthalene-1-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-Benzenedicarboxylic acid, bis(3-methylbutyl) ester (9CI)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
methoxyacetic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-diethoxyethane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dibutyltin dichloride	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-methylimidazole	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4'-methylenedi-o-toluidine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
1-vinylimidazole	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,3-propanesultone	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
chromium trioxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
disodium 4-amino-3-[[4'-[(2,4-diaminophenyl)azo][1,1'-biphenyl]-4-yl]azo]-5-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
hencosafluoroundecanoic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Ammonium-pentadecafluorooctanoate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
sodium peroxometaborate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Disodium-octaborate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Dipentyl phthalate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-aminoazobenzene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
diethyl sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
propylene oxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dimethyl sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
N-methylacetamide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
p-(1,1-dimethylpropyl)phenol	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dicyclohexyl phthalate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dihexyl phthalate (DnHP)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
phenanthrene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dinoseb (ISO)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
butyl 4-hydroxybenzoate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
o-toluidine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-methyl-m-phenylenediamine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
ethylene thiourea	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-o-tolylazo-o-toluidine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-tert-butylphenol	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
nitrobenzene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1-bromopropane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
ethylenediamine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
furan	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
2-methoxyethyl acetate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
6-methoxy-m-toluidine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
C,C'-azodi(formamide)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,7,7-trimethyl-3-(phenylmethylene)bicyclo[2.2.1]heptan-2-one	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-Nonylphenol, branched and linear, ethoxylated [Substances with a linear and/or branched alkyl	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-Heptylphenol, branched and linear	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Nonadecafluorodecanoic acid (PFDA) and its sodium and ammonium salts	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2,3,3,3-tetrafluoro-2-(heptafluoropropoxy)propionic acid, its salts and	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Tris(4-nonylphenyl, branched and linear) phosphite (TNPP) with $\geq 0.1\%$ w/w of 4-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Perfluorobutane sulfonic acid (PFBS) and its salts	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Fluoranthene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Pyrene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Benz[a]anthracene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Cadmium nitrate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Chrysene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Dodecachloropentacyclo[12.2.1.16,9.02,13.05,10]octadeca-7,15-diene ("Dechlorane Plus" TM)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Reaction products of 1,3,4-thiadiazolidine-2,5-dithione, formaldehyde and 4-heptylphenol,	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Perfluorononan-1-oic acid (2,2,3,3,4,4,5,5,6,6,7,7,8,8,9,9,9-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-(1,1,3,3-tetramethylbutyl)phenol, ethoxylated	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
hexahydro-2-benzofuran-1,3-dione	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Methylhexahydrophthalic anhydride	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Sodium perborate; perboric acid, sodium salt	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Cadmium sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
reaction mass of 2-ethylhexyl 10-ethyl-4,4-dioctyl-7-oxo-8-oxa-3,5-dithia-4-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-benzenedicarboxylic acid, di-C6-10-alkyl esters; 1,2-benzenedicarboxylic acid, mixed	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
5-sec-butyl-2-(2,4-dimethylcyclohex-3-en-1-yl)-5-methyl-1,3-dioxane [1], 5-sec-butyl-2-(4,6-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Perfluorohexane-1-sulphonic acid and its salts	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-(1,1,3,3-tetramethylbutyl)phenol, ethoxylated [covering well-defined substances and UVCB	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-ethylhexyl 10-ethyl-4,4-dioctyl-7-oxo-8-oxa-3,5-dithia-4-stannatetradecanoate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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dibutylbis(pentane-2,4-dionato-O,O')tin	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-(2H-benzotriazol-2-yl)-4,6-ditertpentylphenol	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Terphenyl, hydrogenated	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-Benzenedicarboxylic acid, dihexyl ester, branched and linear	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
diisohexyl phthalate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
pentacosafuorotridecanoic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-Benzenedicarboxylic acid, dipentyl ester, branched and linear	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4-isobutylethylidenediphenol	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-benzyl-2-dimethylamino-4-morpholinobutyrophenone	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
3-ethyl-2-methyl-2-(3-methylbutyl)-1,3-oxazolidine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
n-pentyl-isopentylphthalate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,3-BENZENEDIOL, TRINITRO-, LEAD SALT	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Hydrazine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Disodium tetraborate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Boric acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4'-Oxydianiline and its salts	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Aluminosilicate Refractory Ceramic Fibres	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Zirconia Aluminosilicate Refractory Ceramic Fibres	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Acids generated from chromium trioxide and their oligomers	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4-Nonylphenol, branched and linear [substances with a linear and/or branched alkyl chain with a	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Trixylyl phosphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-ethoxyethanol	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Carbonic acid, cobalt(2+) salt (1:1)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Acetic acid, cobalt(2+) salt	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Cobalt-dinitrate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Cobalt sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-ethoxyethyl acetate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Strontium-chromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
N-methyl-2-pyrrolidone	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2,3-trichloropropane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Calcium-arsenate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
bis(2-methoxyethyl) ether	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
potassium hydroxyoctaoxodizincatedichromate(1-)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead dipicrate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
N,N-dimethylacetamide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
arsenic acid	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2-methoxyaniline	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
trilead diarsenate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-dichloroethane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
pentazinc chromate octahydroxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Formaldehyde, polymer with benzenamine	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-Benzenedicarboxylic acid, bis(2-methoxyethyl) ester	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
trichloroethylene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
triethyl arsenate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4'-diaminodiphenylmethane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dibutyl phthalate (DBP)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
bis(2-ethylhexyl) phthalate (DEHP)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead hydrogen arsenate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Butylbenzylphthalate (BBP)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2,4-dinitrotoluene	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Anthracene oil; Anthracene oil	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Anthracene oil, anthracene paste; Anthracene Oil Fraction	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Anthracene oil, anthracene paste, anthracene fraction; Anthracene Oil Fraction	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Anthracene oil, anthracene paste, distn. lights; Anthracene Oil Fraction	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Anthracene oil, anthracene-low; Anthracene Oil Fraction	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
diisobutyl phthalate (DIBP)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead chromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Lead chromate molybdate sulfate red	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Lead sulfochromate yellow	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Pitch, coal tar, high-temp.	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Tris(2-chloroethyl) phosphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
ammonium dichromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
potassium chromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
potassium dichromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
sodium chromate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Boric acid, disodium salt, hydrate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead diazide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Cadmium-fluoride	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
pyrochlore, antimony lead yellow	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead dinitrate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium chloride	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Silicic acid, lead salt	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead oxide sulfate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Lead-titanium-trioxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
pentalead tetraoxide sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Trilead-dioxide-phosphonate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
tetralead trioxide sulphate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dioxobis(stearato)trilead	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Lead titanium zirconium oxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Borate(1-), tetrafluoro-, lead (2+)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead cyanamidate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium hydroxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Acetic acid, lead salt, basic	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Sulfurous acid, lead salt, dibasic	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Silicic acid (H ₂ Si ₂ O ₅), barium salt (1:1), lead-doped	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
[phthalato(2-)]dioxotrilead	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Fatty acids, C16-18, lead salts	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead(II) methanesulphonate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,3,5-tris-[(2S and 2R)-2,3-epoxypropyl]-1,3,5-triazine-2,4,6-(1H,3H,5H)-trione	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
phenolphthalein	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
dichromium tris(chromate)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
2,2'-dichloro-4,4'-methylenedianiline	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
formamide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
tetraethyllead	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4'-bis(dimethylamino)benzophenone	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
N,N,N',N'-tetramethyl-4,4'-methyldianiline	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-dimethoxyethane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,2-bis(2-methoxyethoxy)ethane	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
lead di(acetate)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium carbonate	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
[4-[4,4'-bis(dimethylamino)benzhydrylidene]cyclohexa-2,5-dien-1-	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
4,4'-bis(dimethylamino)-4''-(methylamino)trityl alcohol [with ≥ 0.1% of Michler's ketone (EC No.	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
bis(pentabromophenyl) ether	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Diboron-trioxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium oxide (non-pyrophoric)	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
cadmium sulphide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
orange lead	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
trilead bis(carbonate) dihydroxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
Lead oxide	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity
[4-[[4-anilino-1-naphthyl]]4-(dimethylamino)phenyl]methylene]cyclohexa-2,5	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

Form Rev - F

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
α,α -Bis[4-(dimethylamino)phenyl]-4 (phenylamino)naphthalene-1-methanol [with \geq	MINI50 TERM SMT SOLDER NAIL LT MATTE SN	1,000	1,000.0000001	Impurity

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
glass, oxide, chemicals	PS-ST GF30 Black	*Note	320,000	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold)	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold)	*Note	2,500	Yes
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes

***Note:** For GADSL substance declarable/prohibited threshold values, please reference <http://www.gadsl.org/>

Exemptions

Part Name	Exemption
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5 μ g/cm ² /week)
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21


Contained Substances Exceeding Threshold

None

Form Rev - F

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China ROHS Declaration Information

Part Number	0349126080		Hazardous Substances				
Part Name	MINI50 RAHDR SMT 8CKT BLK POL A T&R						
Part Information							
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MINI50 RAHDR SMT 8CKT BLK POL A T&R		○	○	○	○	○	○
MINI50 HSNG RAHDR SMT 8CKT BLK POL A		○	○	○	○	○	○
MINI50 TERM SMT SOLDER NAIL LT MATTE SN		○	○	○	○	○	○
MINI50 TERM SMT SOLDER NAIL RT MATTE SN		○	○	○	○	○	○
MINI50 TERM BLD 0.50X15.57 AU		○	○	○	○	○	○

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Jan 4, 2021

Form Rev - F

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